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# Silicon Carbide Schottky Diode

1700 V, 10 A

# **NDC10170A**

# **Description**

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

#### **Features**

- Max Junction Temperature 175°C
- Avalanche Rated 156 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery

### **Applications**

- Industrial Motor Loads, Wind Generation Inverter, Solar Inverter, UPS
- Power Switching Circuits

#### **Die Information**

 Wafer Diameter: 6 inch
 Die Size: 2660 × 2660 μm (include Scribe Lane)

• Metallization:

Top: Ti/TiN/AlSiCuBack: Ti/NiV/Ag

• Die Thickness: Typ. 200 μm

• Bonding Pad Size:

• Anode: 1985 × 1985 μm

• Recommended Wire Bond (Note 1)

• Anode:  $15 \text{ mil} \times 2$ 

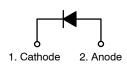
NOTE:

1. Based on TO-247 package

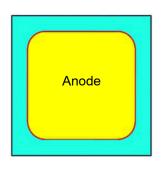


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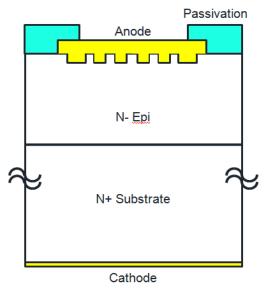
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**Schottky Diode** 



# **CROSS SECTION**



# **ORDERING INFORMATION**

See detailed ordering and shipping information on page 3 of this data sheet.

# **ABSOLUTE MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Peak Repetitive Reverse Voltage	1700	V	
E <sub>AS</sub>	Single Pulse Avalanche Energy (Notes 2 and 4	156	mJ	
I <sub>F</sub>	Continuous Rectified Forward Current @ T <sub>C</sub> < 157°C		10	Α
	Continuous Rectified Forward Current @ T <sub>C</sub> <	16		
I <sub>F, Max</sub>	Non-Repetitive Peak Forward Surge Current	T <sub>C</sub> = 25°C, 10 μs	868	Α
		T <sub>C</sub> = 150°C, 10 μs	798	Α
I <sub>F,SM</sub>	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t <sub>p</sub> = 8.3 ms	105	Α
Ptot	Power Dissipation	T <sub>C</sub> = 25°C	185	W
		T <sub>C</sub> = 150°C	31	W
T <sub>J</sub> , T <sub>STG</sub>	T <sub>STG</sub> Operating and Storage Temperature Range		-55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. E<sub>AS</sub> of 156 mJ is based on starting T<sub>J</sub> = 25°C, L = 0.5 mH, I<sub>AS</sub> = 25 A, V = 50 V.

3. I<sub>FMax</sub>, and I<sub>FSM</sub> surge test value are limited by measurement limitation, it's not product capability

4. DC, E<sub>AS</sub> and Curve test result base on TO247 package

#### THERMAL CHARACTERISTICS

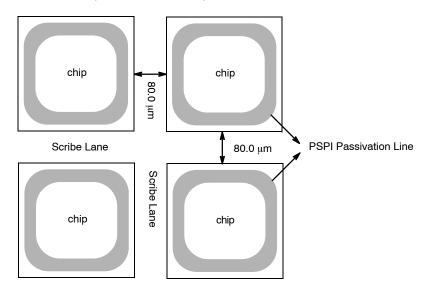
Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max	0.81	°C/W

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 10 A, T <sub>J</sub> = 25°C	-	1.5	-	V
		I <sub>F</sub> = 10 A, T <sub>J</sub> = 125°C	-	1.87	-	
		I <sub>F</sub> = 10 A, T <sub>J</sub> = 175°C	-	2.19	-	
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 1700 V, T <sub>J</sub> = 25°C	-	0.09	40	μΑ
		V <sub>R</sub> = 1700 V, T <sub>J</sub> = 125°C	-	0.42	60	]
		V <sub>R</sub> = 1700 V, T <sub>J</sub> = 175°C	-	2.46	100	]
Q <sub>C</sub>	Total Capacitive Charge	V = 800 V	-	74	=	nC
С	Total Capacitance	V <sub>R</sub> = 1 V, f = 100 kHz	-	856	=	pF
		V <sub>R</sub> = 400 V, f = 100 kHz	-	69	-	
		V <sub>R</sub> = 800 V, f = 100 kHz	-	48	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# The Configuration of Chips (Based on 6 inch Wafer)

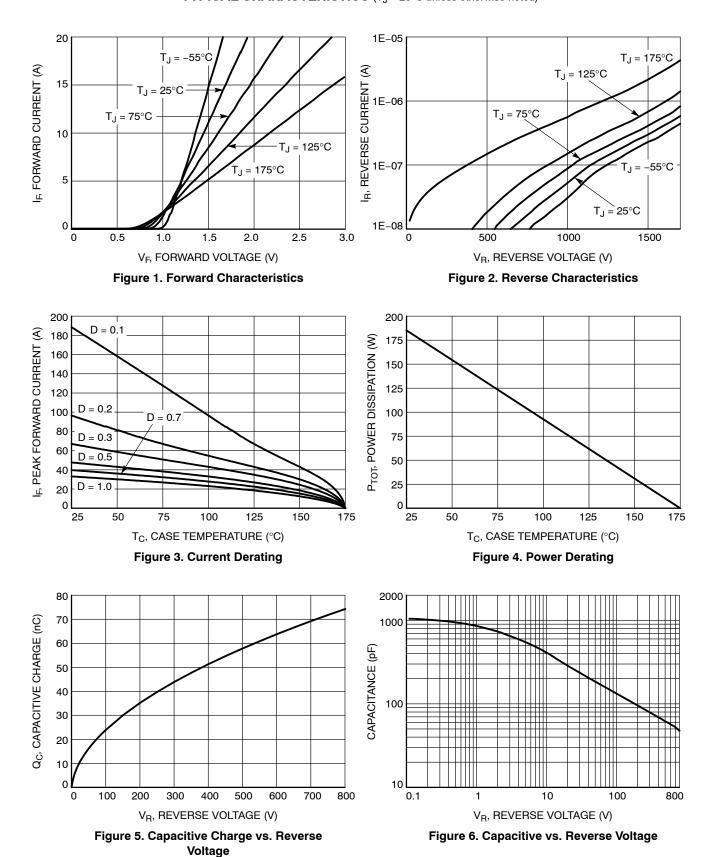


Sawn-on-film frame packing based on tested wafer

# **ORDERING INFORMATION**

Part Number	Die Size with SL (μm)	Package	Shipping	
NDC10170A	2660 x 2660	N/A	Wafer Sales	

# **TYPICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted)



# TYPICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise noted)

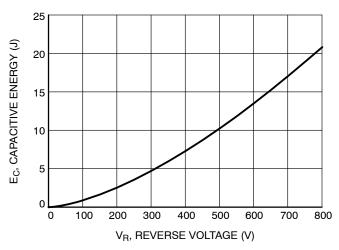


Figure 7. Capacitance Stored Energy

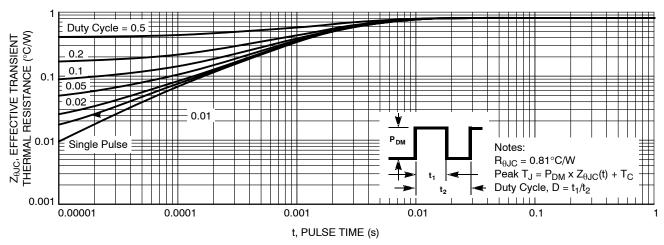


Figure 8. Junction-to-Case Transient Thermal Response Curve

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